

Title (en)
SANDWICH-STRUCTURED INTELLIGENT POWER MODULE

Title (de)
INTELLIGENTES LEISTUNGSMODUL IN SANDWICH-BAUWEISE

Title (fr)
MODULE DE PUISSANCE INTELLIGENT DE STRUCTURE SANDWICH

Publication
EP 1183916 A1 20020306 (DE)

Application
EP 00938710 A 20000530

Priority

- DE 19924993 A 19990531
- EP 0004945 W 20000530

Abstract (en)
[origin: WO0074445A1] According to the invention, the power substrate is used as a base plate in a housing (1) which, together, form a standardized power part from whose top surface (11) connection pins (5) project. Said projection pins are soldered inside interfacial connection via holes of the control printed circuit board (4). The printed circuit board (4) comprises contact pads (7) which are located in an open strip area (6) and which serve as control terminals and power terminals by means of which the module can be soldered directly into the slotted opening of a system printed circuit board (8).

IPC 1-7
H05K 1/14; **H01L 25/16**

IPC 8 full level
H01L 25/16 (2006.01); **H05K 1/14** (2006.01); **H05K 1/18** (2006.01); **H05K 3/34** (2006.01); **H05K 3/36** (2006.01)

CPC (source: EP US)
H01L 25/162 (2013.01 - EP US); **H05K 1/144** (2013.01 - EP US); **H05K 3/366** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 2201/048** (2013.01 - EP US); **H05K 2201/09172** (2013.01 - EP US); **H05K 2201/09645** (2013.01 - EP US)

Citation (search report)
See references of WO 0074445A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0074445 A1 20001207; CN 1271900 C 20060823; CN 1352869 A 20020605; DE 19924993 A1 20001221; DE 19924993 C2 20021010; EP 1183916 A1 20020306; JP 2003501811 A 20030114; US 6646884 B1 20031111

DOCDB simple family (application)
EP 0004945 W 20000530; CN 00808051 A 20000530; DE 19924993 A 19990531; EP 00938710 A 20000530; JP 2001500610 A 20000530; US 98038202 A 20020404